# Low Intensity Diamond Detector Beam Profiler

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# I Introduction:

- Goal and framework: beam profilers – EURISOL, SPIRAL2, SPARC... & focal plane of the associated spectrometers

II The synthetic diamond: (properties, fabrication, principle of detection)

- Single-crystal and polycrystalline sensors
- Response and charge collection = f(material quality & thickness, ion Z&E, U)

### III Non-segmented detectors:

- Construction at LPC and test at GSI (classical electronics) and GANIL (sampling)
- Stability of the signal in time; pulse shape analysis (PSA)

### IV Double-sided multi-strip detectors:

- construction at LPC and tests at GANIL (PSA); analysis in progress

# V Conclusions and prospective

## I. Requirements for a (radioactive) beam profiler working below 10<sup>6</sup> pps:

- The beam profile (X,Y) resolution of 1mm over an active area of up to 50x50mm<sup>2</sup>.
- The device should operate at beam intensities as low as ~1 pps and up to ~10<sup>6</sup>pps.
- The detector should exhibit a fast rise time for timing applications (TOF ~0,5 ns) as well as a short response time to enable operation at ~10<sup>6</sup> pps.
- The detector should have a large dynamic range both very light and very heavy ions with energies ranging from a few to ~250 MeV/nucleon should be detectable.
- The detectors should be **robust and radiation hard** so as to reduce to a minimum their replacement or removal for repair.
- Provide for an accurate and precise measurement of the intensity.
- For safety reasons the detectors must have a good vacuum integrity.
- Insensitive to the decay of the radioactive ions (ie., e-,e+,g, etc).
- From a practical point of view (eg, use by operators during beam tuning) the detectors should be **as simple and straightforward** to operate as possible.
- A promising alternative: the large area synthetic polycrystalline diamond (chemical vapour deposition CVD), have properties matching very closely those needed to fulfil the above requirements

# **R&D EURISOL Task 6 in LPC and SPARC Task 4.1 at FAIR to determine:**

- a) the suitability of CVD diamond to detecting heavy ions;
- b) The feasibility and testing (by pulse shape analysis) of prototype double-sided strip detectors capable of providing event-by-event position measurement and timing PSA



E.-K. Souw, R.J. Meilunas / Nucl. Instr. and Meth. in Phys. Res. A 400 (1997) 69-86



Fig. 3. Pulse height distributions. From 400  $\mu$ Ci-5.49 MeV Am<sup>241</sup>  $\alpha$ -particle source measured in vacuum by CVD diamond detector No. 2 after 3 different time delays: (a) 0 s (b) 2 s and (c) 4 s Bias voltage: -200 V; acquisition time: 1 s. Note, vertical scale is not the same for every PHDs, but individually adjusted to allow a better estimate of PHD peak positions.

II The CVD diamond detectors may behave in very different ways:

#### Single-crystal diamond

detector (CEA Saclay) of 20 µm thickness, adaped to the range. (courtesy of J.-L. Lecouey –LPC)

The signal is 4 lower (left peak) than in a Si detector (right)

# <sup>241</sup>Am: α of 5.5MeV Range ~15 μm

# Polycrystalline-crystal diamond drawback:

the bulk polarization **Solutions:** 

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- Previous radiation;
- Subbandgap light;
- Electronic procedure;
- -Thermic procedure
- Good material!!!
- the salutary solution

### III Not-segmented detectors: pollycristalline diamond

**Cleaning:** eau régale + ultra-sounds

(1/5 H<sub>2</sub>O + 3/5 HCI + 1/5 HNO<sub>3</sub>)

**Electrodes:** Au (ageing) or AI;

if not: CrAu, TiAu, )

**Contacts:** bonding

(AI wire – soldering T + ultra-sounds)

Voltage:  $\pm$  1V/  $\mu$  or higher

Irradiation: growth face or nucleation face – to be compared



Range<<d: transit electrons





Range<<d: transit holes

















Table 3. Synthetic results concerning the shape of the signal induced by 634 MeV <sup>58</sup>Ni ions, having a range of ~ 60  $\mu$ m in a uni-strip diamond detector P1N ELA of 300  $\mu$ m at E = 2,5 V/ $\mu$ .

irradiated face	G face U (V) long tranzit	<v<sub>extrem&gt; (mV)</v<sub>	Rms V (mV)	<q> (mV*ns)</q>	Rms Q (mV*ns)	tr (ns)	rms tr (ns)	<w<sub>1/3&gt; (ns)</w<sub>	Rms w (ns)
G	+750 holes	6.9	1.0	162	25	7.4	1.3	24.1	4.0
G	-750 electrons	9.9	1.5	142	23	4.0	0.61	14.8	0.84
Ν	+750 electrons	9.2	2.0	138	31	4.2	0.68	14.6	1.1
Ν	-750 holes	8.8	1.2	166	21	6.1	1.1	19.8	2.8

The important conclusion emerging from Table 3 is that, when the range of the ion is much shorter then the detector thickness, so that the lengths of the distances of drift of the two types of carriers in their path to the electrode that will collect them are different, the voltage has to be chosen in such a way that the holes have the shortest drift road, regardless of the irradiated face. This will have several beneficial effects: the signal amplitude will be greater, because the charge carrier collection will be better, the signals will be shorter, being characterized by a faster rise time and a shorter duration. The quality of the signals, somehow better on the fourth line of the table as compared to that on the first line - both of them concerning the long drift distance for the holes – may show that the probability of hole catching is a little bit smaller when their road leads to the growth side, with bigger diamond crystallites and therefore a higher quality (for the fourth line) than when their road leads to wards the nucleation side, enclosing more graphite (first line).



When R<d, the signal is higher and faster when the **electrons** drift on a **longer** way then the **holes**. Similar results for det2



## IV Multi-strip detctors: Company 1 - ELP vs ELS

ELP (Electronic Premium Grade) – processed from a polycrystalline wafer with a starting thickness of 1 mm; the final thickness is achieved by removal from the nucleation surface; therefore, thinner the thickness of an ELP plate is, higher its quality; but under 0.2 mm, the risk of breaking in the process of lapping and polishing is much increasing;

ELS (Electronic Standard Grade) – processed from a polycrystalline wafer with a minimum removal of 100 µm. Comparing the two types of material was one of the objectives of our study.



Strip pitch: 0.9mm interstrip gap: 0.1mm efficiency: 90%

The BERGER files for the masks & PCBs were done at LPC

Flange and connectors





### Les tests au GANIL: sur la ligne SME (sortie moyenne énergie)



 Table 4. lons used in GANIL
 Plaque + détecteur + alumine

~2,5 m	GANIL	GANIL	GANIL	GANIL	LPC
	<sup>70</sup> Zn	<sup>36</sup> S	<sup>36</sup> S	<sup>16</sup> O	a
E/A (MeV)	8.7	7.2	3.9	13.7	1.2
Range (µ) ELS	63	48	26	225	15
range (µ) ELP	55	42	22	198	13





#### Det iv ELP, 350 μ -200 V, E=0.6V/μ board 3; O: 13.7 AMeV

#### Det iv ELP, 350µ, -200 V, E=0.6V/µ, board 3; O:13.7 AMeV

the 4 channels of Matacq board 3 give similar results



#### Det iv ELP, 350µ -200 V, E=0.6V/µ, board 3; O :13.7 AMeV







*Résultats pour les détecteurs multipiste:* images prises sur l'oscilloscope LeCroy



Signals induced by <sup>36</sup>S of 7.2 AMeV in the detector III of ELS type



Signals induced by <sup>36</sup>S of 7.2 AMeV in the detector III of ELS type: examples of cross-talk between neighbouring strips on the irradiated face (blue and green)



*Résultats pour les détecteurs multipiste:* images prises sur l'oscilloscope LeCroy

Signals induced by <sup>36</sup>S of 3.9 AMeV in the detector IV of ELP type (-330 V)

5.00 m

5.00 m



Signals from the strip no. 9 of the face a) - left (yellow curve) and from the strip 9 of the face b) - right (blue curve), amplified with the new preamplifier PRL developed at LPC; the signals were induced by the <sup>70</sup>Zn ions of 8.7 AMeV in the detector IV of ELP type for a voltage of -300 V applied on the face a) (growth), irradiated

#### Signaux coincidentes sur les deux faces du détecteur



HT sur la face a) irradiée (1V/µ)

Signals induced by 70Zn of 8.7 AMeV in the detector IV of ELP type

### V. Conclusions & prospective:

# -The CVD polycrystalline diamond based double sided strip detectors seems to be well suited to the requirements for a beam profiler for characterising low intensity radioactive heavy ion beams:

- material: ELP (small bulk polarization; signal stable in time); P2 from Company 1, for example
- thickness: 200-300  $\mu$  adequate for R~50  $\mu$
- electric field ~1V/ $\mu$ ; HV though Sh < Se
- strip: 1 mm pitch (0.9mm strip, inter-strip gap: 0.1mm), efficiency: 90-99% (localization with 1 mm resolution)
- small cross-talk effects
- signal shape study: ~1.5 ns rise time for 1 strip; PSA may bring interesting information ( $\Delta Q < \Delta V_{extrem}$ )

# -The further characterisation of such detectors and the engineering of the readout electronics and other associated elements of a fully fledged profiler are expected to be carried beyond the present study:

- tests for radiation hardness

- double layer metallization: Ti,(Cr) Au to improve the contact and to avoid the ageing of Au film and its migration inside the diamond wafer;

- more robust electric contacts between PCB and strips?
- line receiver multi-channel preamplifiers for low energies
- acquisition system

-Note: The study of the diamond detector has been the subject for a Janus stage in 2008 (2 students), as well as of a TIPE presentation (3 students) and a M1 stage (1 student) in 2009.

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